

ABSTRACT

[Solution means] The process for producing a printed wiring board of the invention comprises a step of depositing a base metal on at least one surface of an insulating film to form a base metal layer and further depositing copper or a copper alloy to form a conductive metal layer, a step of selectively removing a surface metal layer, which is formed through the above step, by etching to form a wiring pattern, and a step of treating the base metal layer with a treating liquid capable of dissolving and/or passivating the metal that forms the base metal layer. The printed wiring board of the invention comprises an insulating film and a wiring pattern formed on at least one surface of the insulating film, said wiring pattern comprising a base metal layer deposited on the insulating film surface and a conductive metal layer, said base metal layer for forming the wiring pattern being protruded widthwise more than the conductive metal layer for forming the wiring pattern.

[Effect] According to the present invention, most of the metal that forms the base metal layer can be removed, and the base metal layer-forming metal remaining in a slight amount is passivated, so that migration significantly

hardly occurs and a printed wiring board having extremely high reliability can be obtained.